

PATENT ASSIGNMENT COVER SHEET

Electronic Version v1.1
 Stylesheet Version v1.2

EPAS ID: PAT3791000

SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT
CONVEYING PARTY DATA	
Name	Execution Date
FLORIN UDREA	02/03/2016
GIANLUCA CAMUSO	03/08/2016
ALICE PEI-SHAN HSIEH	03/08/2016
CHIU NG	03/11/2016
YI TANG	03/09/2016
RAJEEV KRISHNA VYTILA	03/08/2016
CANHUA LI	03/11/2016
RECEIVING PARTY DATA	
Name:	INFINEON TECHNOLOGIES AMERICAS CORP.
Street Address:	101 N. SEPULVEDA BLVD.
City:	EL SEGUNDO
State/Country:	CALIFORNIA
Postal Code:	90245
PROPERTY NUMBERS Total: 1	
Property Type	Number
Application Number:	15074062
CORRESPONDENCE DATA	
Fax Number:	(949)282-1002
<i>Correspondence will be sent to the e-mail address first; if that is unsuccessful, it will be sent using a fax number, if provided; if that is unsuccessful, it will be sent via US Mail.</i>	
Phone:	9492821000
Email:	docketing@farjami.com
Correspondent Name:	MICHAEL FARJAMI
Address Line 1:	26522 LA ALAMEDA AVE. SUITE 360
Address Line 4:	MISSION VIEJO, CALIFORNIA 92691
ATTORNEY DOCKET NUMBER:	0400847
NAME OF SUBMITTER:	MICHAEL FARJAMI
SIGNATURE:	/MF/
DATE SIGNED:	03/18/2016

Total Attachments: 24

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DECLARATION AND ASSIGNMENT FOR PATENT AND DESIGN APPLICATIONS

UNITED STATES PATENT RIGHTS, OR
UNITED STATES PLUS ALL FOREIGN PATENT RIGHTS

Title of Invention **Bipolar Semiconductor Device with Multi-Trench Enhancement Regions**

As a below named inventor (hereinafter designated as the undersigned), I hereby declare that:

Application not Attached **This declaration is directed to the application attached hereto. If the application is not attached hereto, the application is as identified by the attorney docket number as set forth above and/or the following: 0400847.**

Enter Appln. No. **United States Application Number or PCT International Appln. No. 15/074,062**

Enter Filing Date **filed on March 18, 2016**.

The above-identified application was made or authorized to be made by me.

I believe that I am the original inventor or an original joint inventor of a claimed invention in the application.

I have reviewed and understand the contents of the above-identified application, including the claims.

I acknowledge the duty to disclose information which is material to patentability as defined in Title 37, Code of Federal Regulations § 1.56.

WHEREAS, the undersigned has invented certain at least one claim in the application identified.

Insert Name of Assignee **WHEREAS, Infineon Technologies Americas Corp.**

Insert Address of Assignee **of 101 N. Sepulveda Blvd.; El Segundo, CA 90245 USA**

its heirs, successors, legal representatives and assigns (hereinafter designated as the Assignee) is desirous of acquiring the entire right, title and interest in and to said invention and in and to any Letters Patent(s) that may be granted therefor in the United States of America and

Check Box if Appropriate **☒ in any foreign countries.**

NOW, THEREFORE, for good and valuable consideration, the receipt of which is hereby acknowledged, the undersigned has (have) sold, assigned and transferred, and by these considerations does (do) sell, assign and transfer unto said Assignee the full and exclusive right to the said invention in the United States of America, its territories, dependencies and possessions and the entire right, title and interest in and to any and all Letters Patent(s) which may be granted therefor in the United States of America, its territories, dependencies and possessions, and if the box above is designated, in any and all foreign countries; and to any and all divisions, reissues, continuations, conversions and extensions of all of the above for the full term or terms for which the same may be granted.

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In witness whereof, executed by the undersigned on the date opposite the undersigned name.

Full Name of Inventor:

FLORIN UDREA

07/03/2016

Date



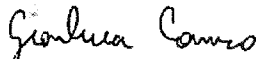
Inventor's Signature

Full Name of Inventor:

GIANLUCA CAMUSO

08/03/2016

Date



Inventor's Signature

Full Name of Inventor: **ALICE PEI-SHAN HSIEH**

Date

Inventor's Signature

Full Name of Inventor: **CHIU NG**

Date

Inventor's Signature

Full Name of Inventor: **YI TANG**

Date

Inventor's Signature

Full Name of Inventor: **RAJEEV KRISHNA VYTLA**

Date

Inventor's Signature

Full Name of Inventor: **CANHUA LI**

Date

Inventor's Signature

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In witness whereof, executed by the undersigned on the date opposite the undersigned name.

Full Name of Inventor: **FLORIN UDREA**

Date

Inventor's Signature

Full Name of Inventor: **GIANLUCA CAMUSO**

Date

Inventor's Signature

Full Name of Inventor:

ALICE PEI-SHAN HSIEH

08-Mar-2016

Date

PS Hsieh

Inventor's Signature

Full Name of Inventor:

CHIU NG

Date

Inventor's Signature

Full Name of Inventor:

YI TANG

Date

Inventor's Signature

Full Name of Inventor:

RAJEEV KRISHNA VYTILA

Date

Inventor's Signature

Full Name of Inventor: **CANHUA LI**

Date

Inventor's Signature

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Full Name of Inventor:

FLORIN UDREA

Date

Inventor's Signature

Full Name of Inventor:

GIANLUCA CAMUSO

Date

Inventor's Signature

Full Name of Inventor: **ALICE PEI-SHAN HSIEH**

Date

Inventor's Signature

Full Name of Inventor: **CHIU NG**

3/11/2016

Date

Chiu Ng
Inventor's Signature

Full Name of Inventor: **YI TANG**

Date

Inventor's Signature

Full Name of Inventor: **RAJEEV KRISHNA VYTILA**

Date

Inventor's Signature

Full Name of Inventor: **CANHUA LI**

Date

Inventor's Signature

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Date

Inventor's Signature

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Date

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ALICE PEI-SHAN HSIEH

Date

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CHIU NG

Date

Inventor's Signature

Full Name of Inventor:

YI TANG

2016/3/19

Date

Inventor's Signature

Full Name of Inventor:

RAJEEV KRISHNA VYTILA

Date

Inventor's Signature

Full Name of Inventor:

CANHUA LI

Date

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V. Raju Krish

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The undersigned agrees to perform all affirmative acts which may be necessary to obtain a grant of (a) valid United States of America patent(s) and any foreign patent(s) to the Assignee and to vest all rights therein hereby conveyed to said Assignee as fully and entirely as the same would have been held by the undersigned if this Assignment and sale had not been made.

The undersigned hereby authorizes and requests the Patent and Trademark Office Officials in the United States of America and in any foreign countries to issue any and all Letters Patent(s) resulting from said application or any continuing, divisional conversion or reissue applications thereof to the said Assignee, as Assignee of the entire interest, and hereby covenants that he has the full right to convey the entire interest herein assigned, and that he has not executed, and will not execute, any agreement in conflict herewith.

The undersigned hereby grants the Assignee's legal representatives the power to insert in this document, before or after it has been executed by the undersigned, any information to identify the instant patent application which may be necessary or desirable in order to comply with the rules of the U.S. Patent and Trademark Office.

The undersigned hereby covenants that no assignment, sale, agreement or encumbrance has been or will be made or entered into which would conflict with this assignment.

The undersigned hereby acknowledges that any willful false statement made in this declaration is punishable under 18 U.S.C. § 1001 by fine or imprisonment of not more than five (5) years, or both.

In witness whereof, executed by the undersigned on the date opposite the undersigned name.

Full Name of Inventor: **FLORIN UDREA**

Date

Inventor's Signature

Full Name of Inventor: **GIANLUCA CAMUSO**

Date

Inventor's Signature

Full Name of Inventor: **ALICE PEI-SHAN HSIEH**

Date

Inventor's Signature

Full Name of Inventor: **CHIU NG**

Date

Inventor's Signature

Full Name of Inventor: **YI TANG**

Date

Inventor's Signature

Full Name of Inventor: **RAJEEV KRISHNA VYTLA**

Date

Inventor's Signature

Full Name of Inventor:

CANHUA LI

3/11/2016

Date



Inventor's Signature